

The diagram illustrates the system architecture for the Intel® TigerLake-U processor in COM Express Type 6 modules. The central component is the **Intel® TigerLake-U** processor.

Left Side (COM Express Type 6 ROW A/B):

- Storage:** SATA3.0 *2
- USB:** USB 2.0 *8
- Interconnect:** SMBus
- PCIe:** PCIe3.0 x5
- Network:** GbE with TSN
- Video:** VGA (with a separate **VGA** block), eDP, and an optional LVDS connection to the **PTN 3460** panel.
- Expansion:** eSPI to LPC, which is connected to a **TPM** (Trusted Platform Module).
- Management:** e.MGMT, connected via I2C, Tx/Rx *2 and FAN, GPIO, HW/M.

Right Side (COM Express Type 6 ROW C/D):

- Memory:** DDR4 SO-DIMM *2
- USB:** USB 3.0 *4
- Display:** DDI1, DDI2, and DDI3
- BIOS:** Connected via SPI
- Expansion:** PEG[x4], Gen4.0

[illegible]

SoC GPIO Pins :

Name	Power Well	Default	GPIO Function	Location
GPP_A14/USB_OC1#/DDSP_HPDP3/I2S3_RXD/DISP_MISC3/DMIC_CLK_B1	+V3P3S	PD	DDI3_HPDP	DH52
GPP_A15/USB_OC2#/DDSP_HPDP4/DISP_MISC4/I2S4_SCLK	+V3P3S	PD	DDI4_HPDP	DK45
GPP_E4/DEVSLP0	+V3P3A	PU	USB2_OC2#	DG8
GPP_E5/DEVSLP1	+V3P3A	PU	USB2_OC1#	DN6
GPP_E3/CPU_GP0	+V3P3A	PU	SMI#	DU5
GPP_E7/CPU_GP1	+V3P3A	PU	SCI#	DF8
GPP_T2	+V3P3A	PD	BOARD_ID1	DT35
GPP_T3	+V3P3A	PD	BOARD_ID0	DN33
GPP_U4	+V3P3A	PD	BOARD_ID3	DG19
GPP_U5	+V3P3A	PD	BOARD_ID2	DG17
GPP_B23/SML1ALERT#/PCHHOT#/GSP1I_CS1#	+V3P3A	PU	ESPI_ALT#	CY50
GPP_H19/TIME_SYNC0	+V3P3S	PU	EC_KBRST#	DJ27

EC GPIO Pins :

Name	Power Well	Default	GPIO Function	Location	Note
KS11/AFD#	+V3P3A	Input	I_RSMRST	J13	
RING#/PWRFAIL#/CK32KOUT/LPCRST#/GPB7	+V3P3A	Output	O_RSMRST	A1	When J13 active HIGH, then PU A1 after 10ms
KSO5/PD5	+V3P3A	Output	ESPI_EN#	J8	PU to Enable COM eSPI out
L80HLAT/BAO/WUI24/GPE0	+V3P3A	Input	GPI0	N2	
EGAD/WUI25/GPE1	+V3P3A	Input	GPI1	A13	
EGCS4/WUI26/GPE2	+V3P3A	Input	GPI2	A12	
EGCLK/WUI27/GPE3	+V3P3A	Input	GPI3	B12	
HSCE#/GPH3/ID3	+V3P3A	Output	GPO0	A9	
HSCK/GPH4/ID4	+V3P3A	Output	GPO1	B8	
HMISO/GPH5/ID5	+V3P3A	Output	GPO2	A8	
HMOSI/GPH6/ID6	+V3P3A	Output	GPO3	B7	

SMBus/I2C Addresses :

Device	address
I219	0XC8
PTN3460BS/F6	0C0h

PCB Footprints

MOSFET BJT



PCB STACK :

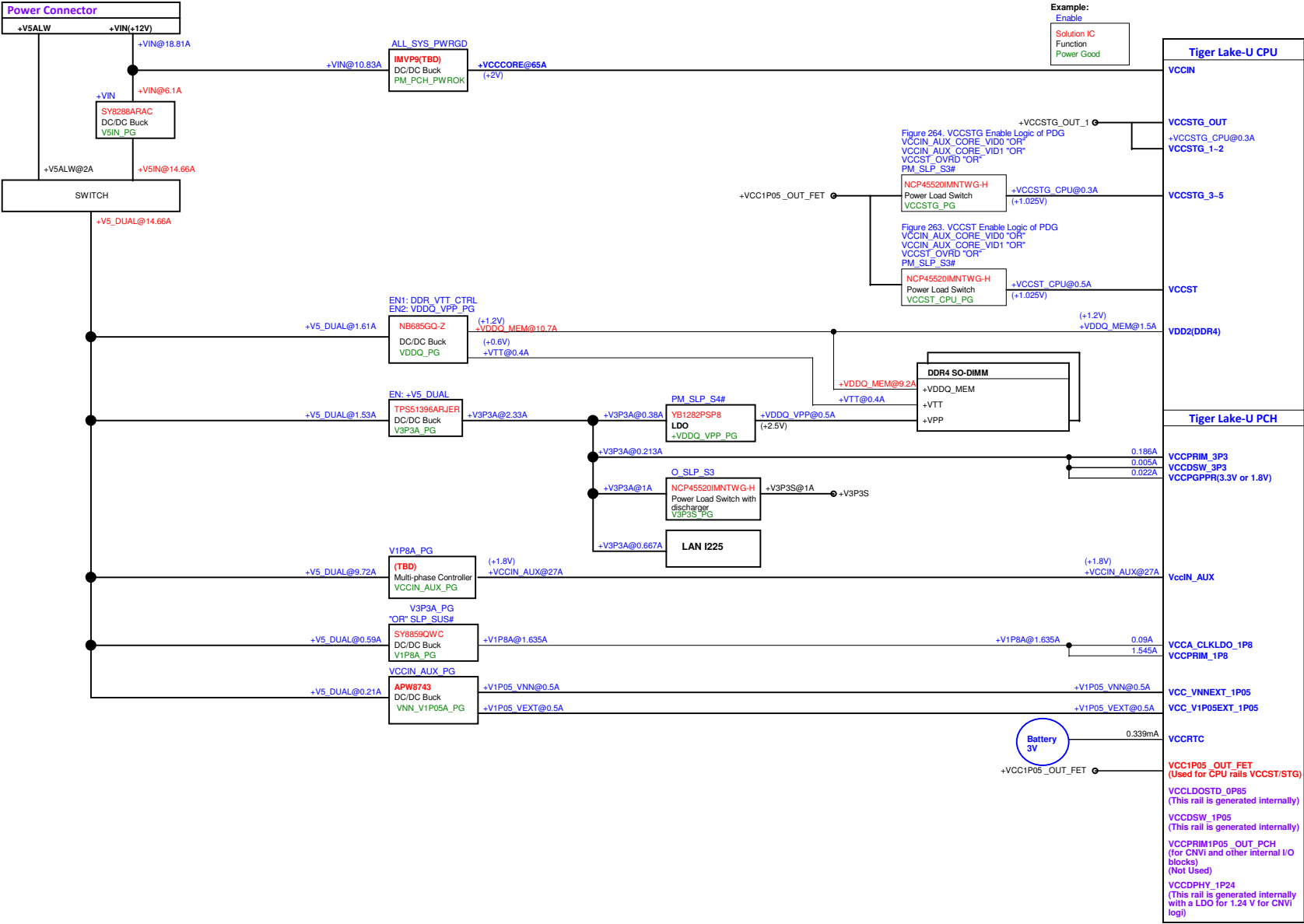
Board: FR4
Impedence: 50ohm +/-10%
Thickness: 2.0mm +/-10%

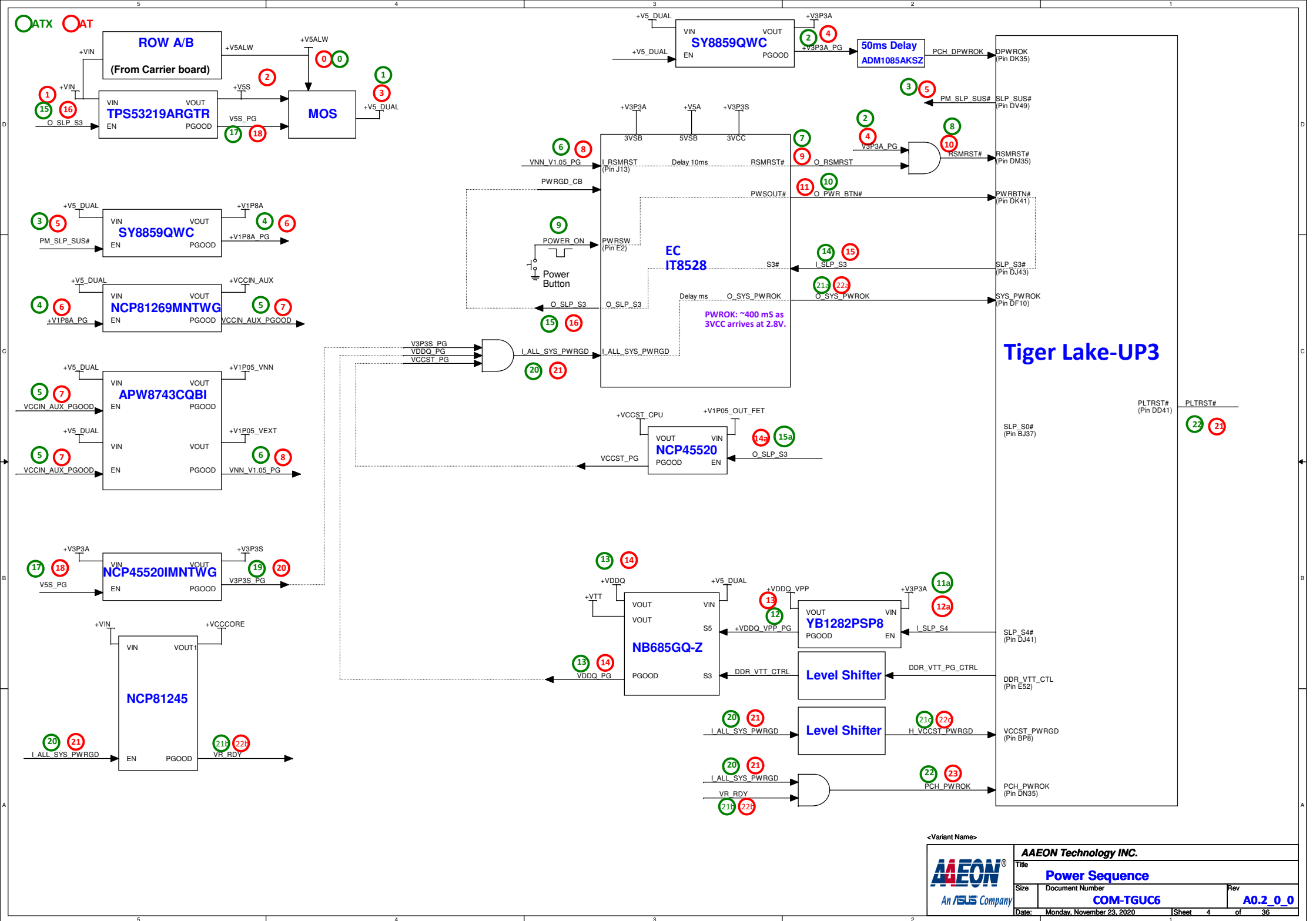
- Layer 1 : Component (Top)
- Layer 2 : GND (GND1)
- Layer 3 : Signal (IN1)
- Layer 4 : GND (GND2)
- Layer 5 : Signal (IN2)
- Layer 6 : POWER (VCC)
- Layer 7 : POWER (VCC)
- Layer 8 : Signal (IN3)
- Layer 9 : GND (GND3)
- Layer 10 : Signal (IN4)
- Layer 11 : GND (GND4)
- Layer 12 : Signal (IN5)
- Layer 13 : GND (GND5)
- Layer 14 : Solder (Bottom)

<Variant Name>


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Power Delivery

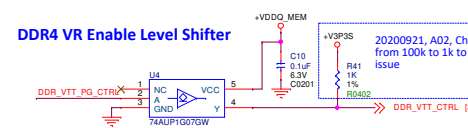




<Variant Name>

		AAEON Technology INC.	
		Title Power Sequence	
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SoC DDR4



SoC HDA/SD

All HDA R
close to SOC

CPU1G

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[17] HDA_BCLK
[17] HDA_SYNC
[17] HDA_SDO
[17] HDA_SDI0

R111 33R0201 HDA_BCLK_R DR38
R112 33R0201 HDA_SYNC_R DU37
R109 33R0201 HDA_SDO_R DT37
R110 0 R0201 HDA_SDI0_R DV37

GPP_R0/HDA_BCLK/I2S0_SCLK
GPP_R1/HDA_SYNC/I2S0_SFRM
GPP_R2/HDA_SDO/I2S0_TXD
GPP_R3/HDA_SDI0/I2S0_RXD
GPP_R4/HDA_RST#
GPP_A7/I2S2_SCLK/DMIC_CLK_A0
GPP_A8/I2S2_SFRM/CNV_RF_RESET#/DMIC_DATA_0
GPP_A10/I2S2_RXD/DMIC_DATA1
GPP_A9/I2S2_TXD/MODEM_CLKREQ/CRF_XTAL_CLKREQ/DMIC_CLK_A1
GPP_A11/PMC_I2C_SDA/I2S3_SCLK
GPP_A13/PMC_I2C_SCL/I2S3_TXD/DMIC_CLK_B0
SNDW_RCOMP

GPP_F8/I2S_MCLK2_INOUT
GPP_D19/I2S_MCLK1
GPP_A23/I2S1_SCLK
GPP_R7/I2S1_SFRM
GPP_R6/I2S1_TXD
GPP_R5/HDA_SDI1/I2S1_RXD
GPP_S6/SNDW3_CLK/DMIC_CLK_A0
GPP_S7/SNDW3_DATA/DMIC_DATA0
GPP_S4/SNDW2_CLK/DMIC_CLK_A1
GPP_S5/SNDW2_DATA/DMIC_DATA1
GPP_S2/SNDW1_CLK/DMIC_CLK_B0
GPP_S3/SNDW1_DATA/DMIC_CLK_B1
GPP_S0/SNDW0_CLK
GPP_S1/SNDW0_DATA

DW15
DW24
DG41
DT38
DV38
DW38
HDA_SDI1_R R114 0 R0201 HDA_SDI1 [17]
DN31
DM31
DK33
DK31
DW35
DV35
DT32
DR35

A01, 20200506, change R109 from 0R to 33R
by PDG request.

R116 200 R0402
SNDW_RCOMP

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CPU1F

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[17] SPKR << SPKR

DC53 GPP_B16/GSPI0_CLK
DA51 GPP_B18/GSPI0_MOSI
DC49 GPP_B17/GSPI0_MISO
DC50 GPP_B14/SPKR/TIME_SYNC1/GSPI0_CS1#
DC52 GPP_B15/GSPI0_CS0#
CY49 GPP_B20/GSPI1_CLK
CY53 GPP_B22/GSPI1_MOSI
CY52 GPP_B21/GSPI1_MISO
DA50 GPP_B19/GSPI1_CS0#
DV21 GPP_C9/UART0_TXD
DT21 GPP_C8/UART0_RXD
DR21 GPP_C11/UART0_CTS#
DW21 GPP_C10/UART0_RTS#
DV19 GPP_C13/UART1_TXD/ISH_UART1_TXD
DT19 GPP_C12/UART1_RXD/ISH_UART1_RXD
DR19 GPP_C15/UART1_CTS#/ISH_UART1_CTS#
DU19 GPP_C14/UART1_RTS#/ISH_UART1_RTS#
DJ21 GPP_C21/UART2_TXD
DG23 GPP_C20/UART2_RXD
DJ19 GPP_C23/UART2_CTS#
DF21 GPP_C22/UART2_RTS#
DV18 GPP_C17/I2C0_SCL
DW18 GPP_C16/I2C0_SDA
DJ23 GPP_C19/I2C1_SCL
DT18 GPP_C18/I2C1_SDA
DU29 GPP_H5/I2C2_SCL
DJ31 GPP_H4/I2C2_SDA
DF29 GPP_H7/I2C3_SCL
DG29 GPP_H6/I2C3_SDA
DF25 GPP_H9/I2C4_SCL/CNV_MFUART2_TXD
DF27 GPP_H8/I2C4_SDA/CNV_MFUART2_RXD

GPP_D14/ISH_UART0_TXD
GPP_D13/ISH_UART0_RXD
GPP_D16/ISH_UART0_CTS#
GPP_D15/ISH_UART0_RTS#/GSPi2_CS1#/IMGCLKOUT5
GPP_B6/ISH_I2C0_SCL
GPP_B5/ISH_I2C0_SDA
GPP_B8/ISH_I2C1_SCL
GPP_B7/ISH_I2C1_SDA
GPP_B10/I2C5_SCL/ISH_I2C2_SCL
GPP_B9/I2C5_SDA/ISH_I2C2_SDA
GPP_E16/ISH_GP7
GPP_E15/ISH_GP6
GPP_D18/ISH_GP5
GPP_D17/ISH_GP4
GPP_D3/ISH_GP3/BK3/SBK3
GPP_D2/ISH_GP2/BK2/SBK2
GPP_D1/ISH_GP1/BK1/SBK1
GPP_D0/ISH_GP0/BK0/SBK0
GPP_RCOMP
GPP_T3
GPP_T2
GPP_U5
GPP_U4

DF27
DW27
DV25
DT25
DB45
DB44
CY39
DB47
DD47
DD44
DJ8
DR7
DR24
DU25
DV31
DU31
DT27
DV27
DR51
DN33
DT35
DG17
DG19
BOARD_ID0
BOARD_ID1
BOARD_ID2
BOARD_ID3
BOARD ID

20200717, A02, Add TP30~TP33 for BIOS request.

[26] TPM_PIRQ#

TP31 TP30 TP20 GPP_C9
TP30 TP20 GPP_C8

20201105, A02, the nets of CPU1.DJ29 & CPU1.DJ31 (I2C
fuction for 80 port) for the PCB spacing of EEPROM of Intel
I225.

COM

[17] I2C3_SCL
[17] I2C3_SDA

I2C3_SCL
I2C3_SDA

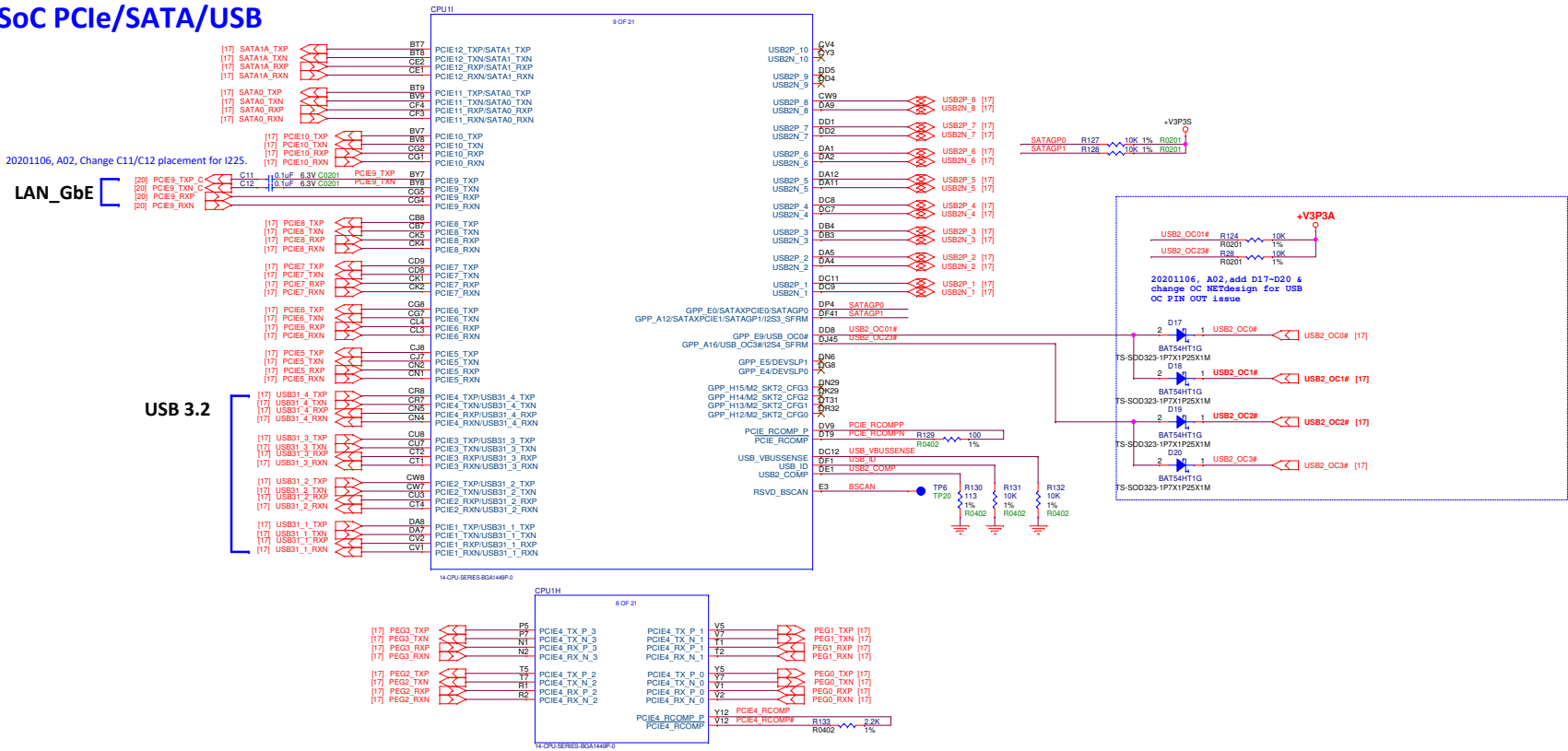
+V3P3S
R122 1K I2C3_SCL
R0201 5%
R121 1K I2C3_SDA
R0201 5%

+V3P3A
R418 X/2 2K
R0402 1%
R419 20K
R0201 1%
+V3P3A
R420 X/2 2K
R0402 1%
R421 20K
R0201 1%
+V3P3A
R422 X/2 2K
R0402 1%
R423 20K
R0201 1%
+V3P3A
R424 X/2 2K
R0402 1%
R425 20K
R0201 1%

<Variant Name>

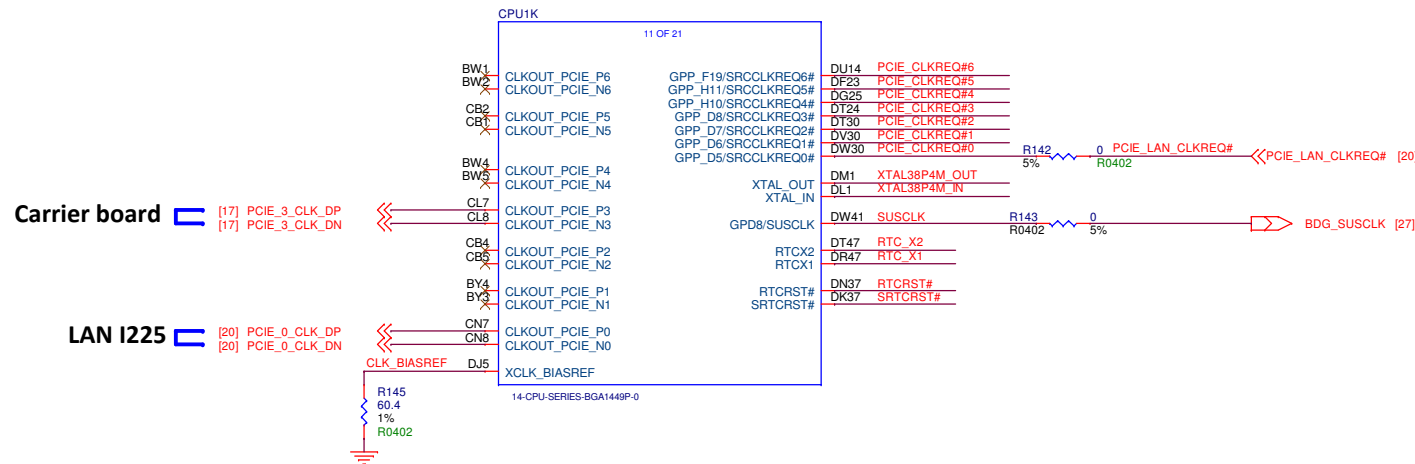
AAEON Technology INC.	
Title	SoC HDA/I2C
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COM-TGUC6	
An ASUS Company	

SoC PCIe/SATA/USB

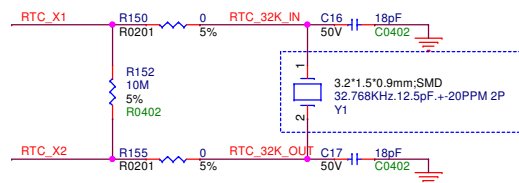


Flex HSIO Lane	0	1	2	3	4	5	6	7	8	9	10	11
HSIO Type and Lane	USB 3.2 Gen 1x1/2x1 #1	USB 3.2 Gen 1x1/2x1 #2	USB 3.2 Gen 1x1/2x1 #3	USB 3.2 Gen 1x1/2x1 #4	PCIe* #5	PCIe* #6	PCIe* #7	PCIe* #8	PCIe* #9	PCIe* #10	PCIe* #11	PCIe* #12
	PCIe* #1	PCIe* #2	PCIe* #3	PCIe* #4								SATA 1
												SATA 0

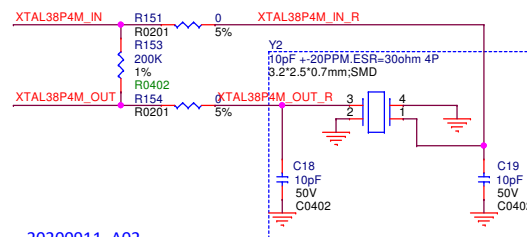
SoC PCIE_CLK/ RTC/ XTAL



CLKOUT_PCIE_P / N [6:4, 2:1] = Support up to PCIe Gen3
CLKOUT_PCIE_P / N [3, 0] = Support up to PCIe Gen4

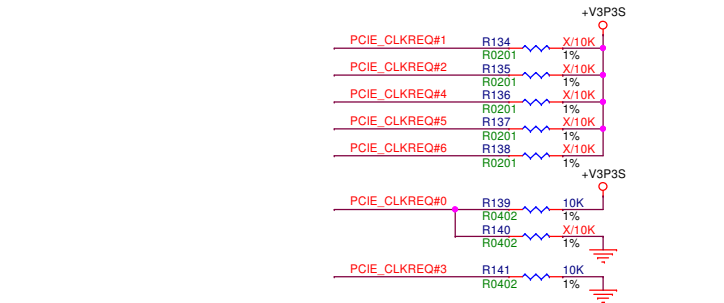


20200911, A02, Change P/N of Y1 from 1231327631 to 1231327632 by test result.

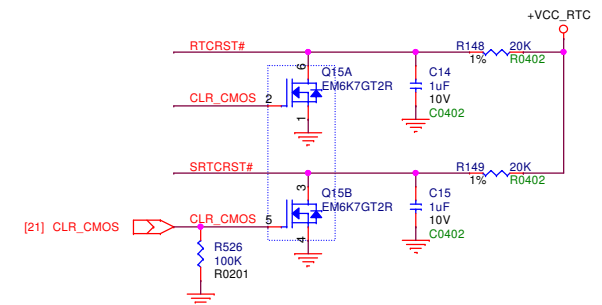
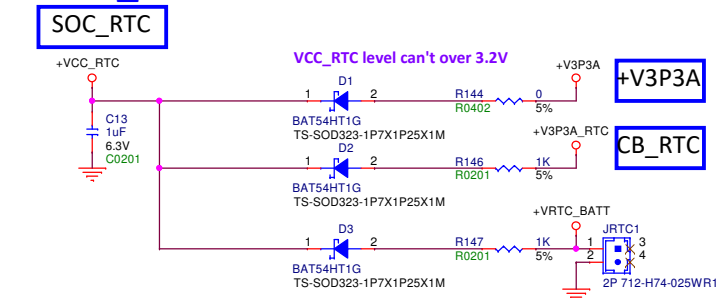


20200911, A02,

1. Change P/N of Y2 from 1231038450 to 1231038451 by test result.
2. Change value of C18/C19 from 15pF to 10pF by test result.



+VCC_RTC



RTC RESET

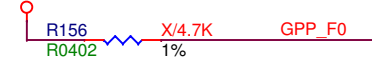
Status of CLR_CMOS at G3/S5/S0		
CLR_CMOS	RTCST#	SRTCST
HIGH (SW"SHORT")	RESET	RESET
LOW (SW"OPEN")	Normal Operation	Normal Operation

SoC CNVi

GPP_F0	XTAL SEL1
0 *	38.4/19.2MHZ (DEFAULT)
1	24MHZ (25 MHZ WHEN XTAL FREQ DIVIDER NON ZERO)

* Default, Internal Pull-Down 20k
24 MHz crystal is not supported

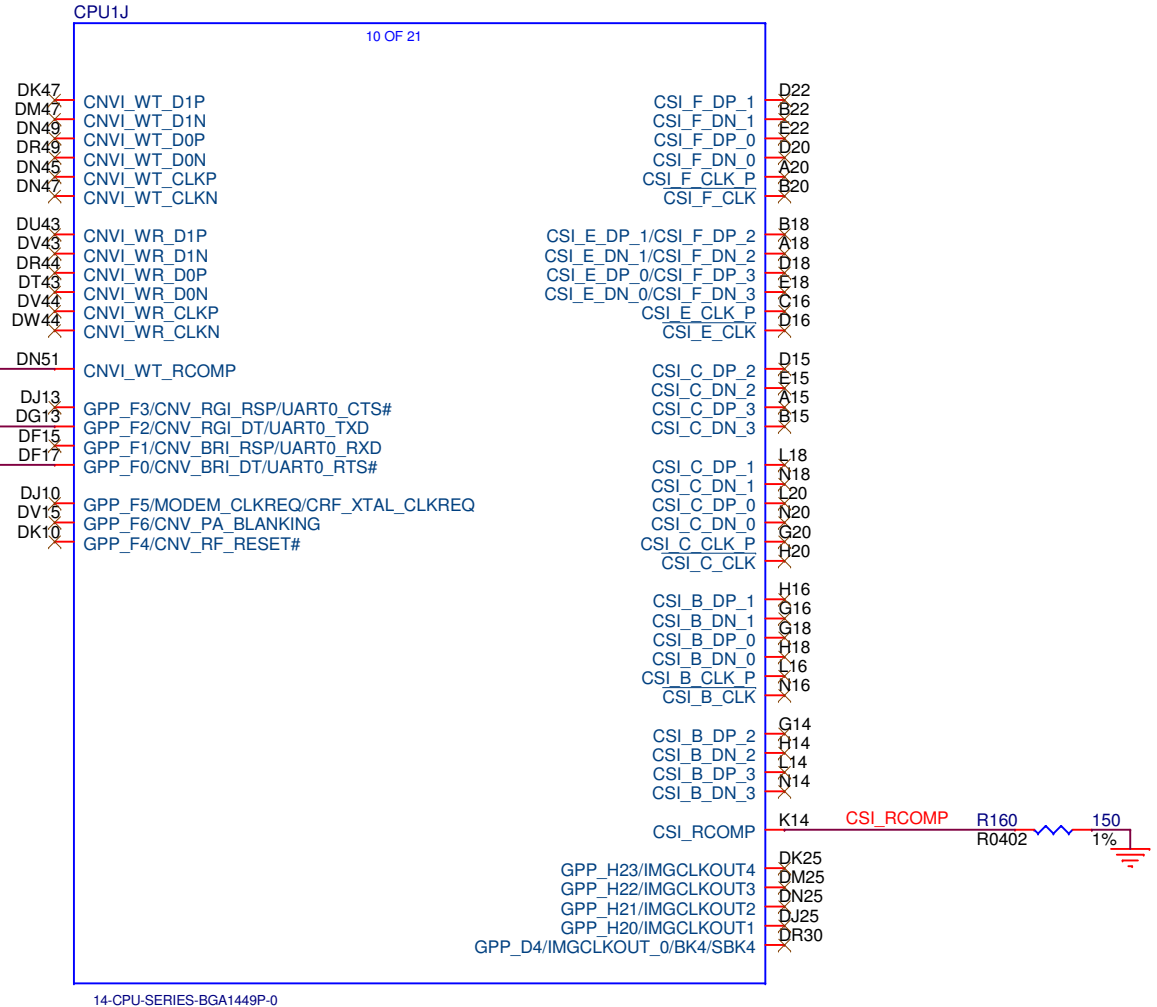
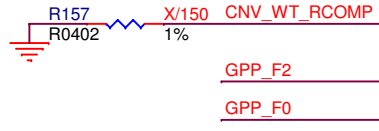
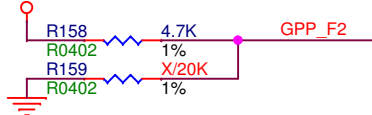
+V3P3A



GPP_F2	M.2 CNVi Mode Select
0 *	Integrated CNVi enabled.
1	Integrated CNVi disabled.

This strap does not have an internal pull-up or pull-down. A weak external pull-up is required.

+V3P3A



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<Variant Name>

**AAEON Technology INC.**

Title

SoC CNVi

Size

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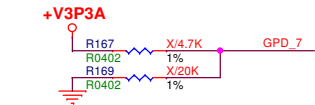
Date: Monday, November 23, 2020

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SoC System

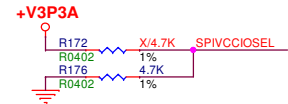
GPD7	Reserved
	This strap should sample LOW. There should NOT be any on-board device driving it to opposite direction during strap sampling.

This strap has a 20 kohm ± 30% internal pull-down.

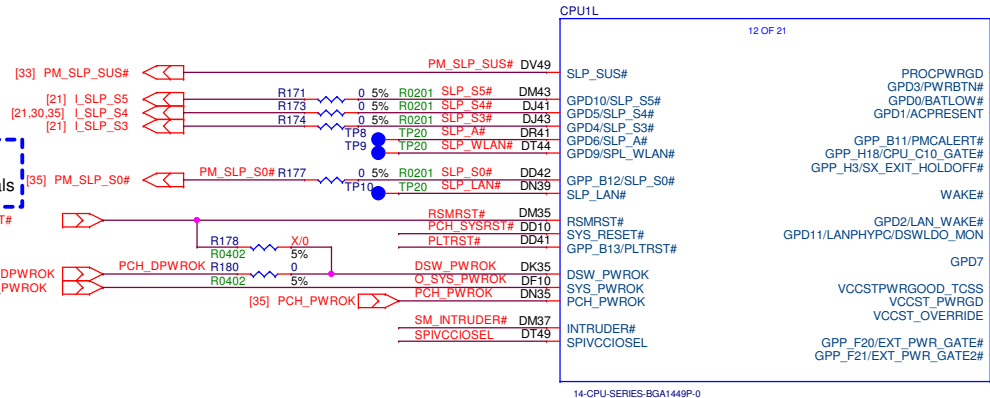
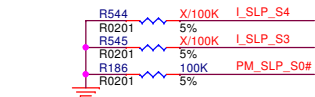
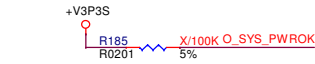
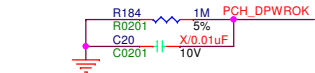


SPIVCCIOSEL	STRAP FOR SPI 1.8V/3.3V SELECTION
0 *	3.3 V
1	1.8 V

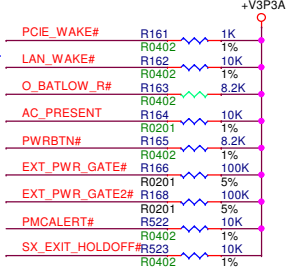
An external resistor is required.



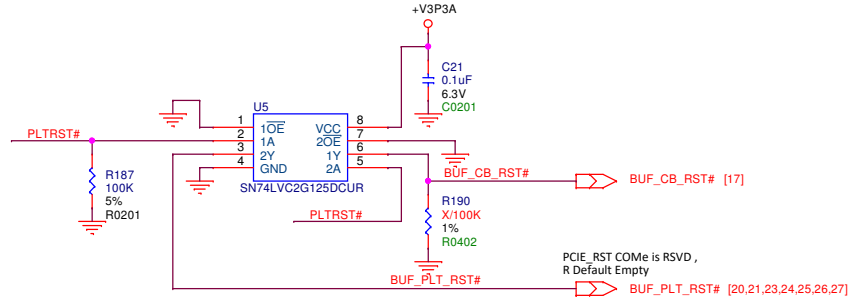
PDG, DSW_PWROK and RSMRST# are always separate power good signals



20201106, A02, Mount R162 for I225.



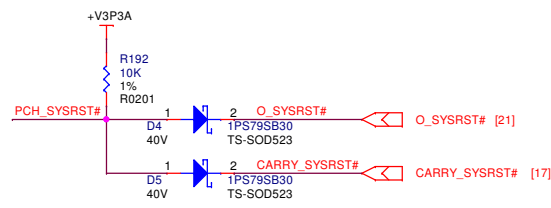
Dual Bus Buffer Gate with 3-State Outputs



Carry Board
PCIE_RST*2

eSPI to LPC
eDP to LVDS
DDI to VGA
LAN
EC
TPM

SYSRST#

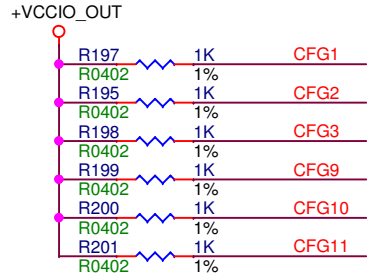
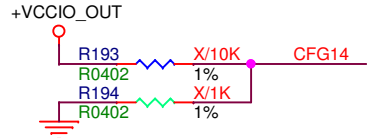


<Variant Name>

SoC Strap

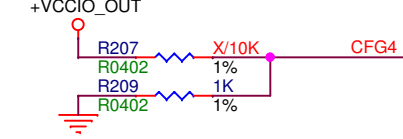
CFG14	PEG* Static x4 Lane Numbering Reversal
0	Lane numbers reversed
1 *	Normal operation

The CFG signals have a default value of '1'



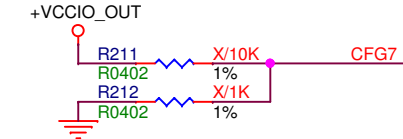
CFG4	eDP Presence
0 *	ENABLE
1	DISABLE

The CFG signals have a default value of '1'

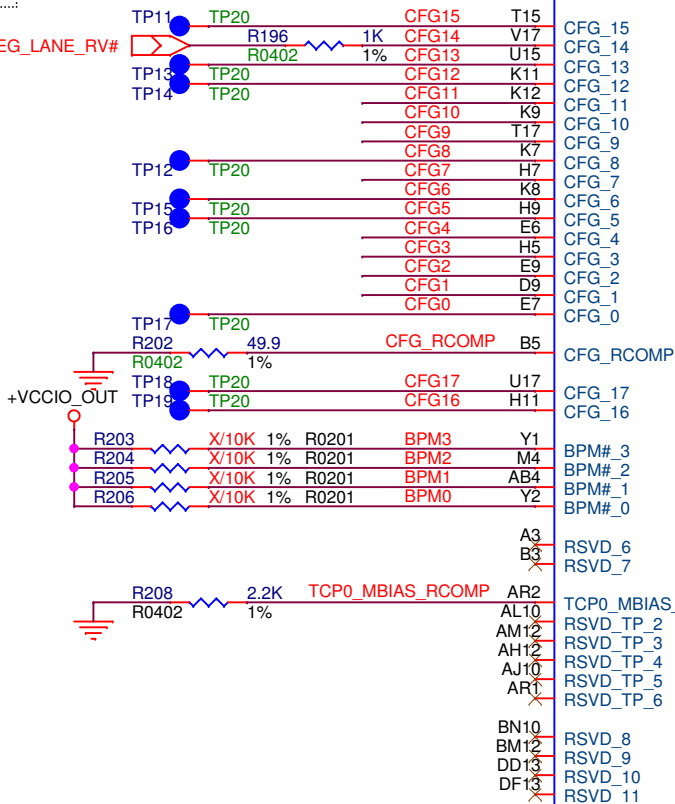


CFG7	PEG Training
0	PEG Wait for BIOS for training
1 *	PEG Train immediately following RESET# de assertion

The CFG signals have a default value of '1'



[17] PEG_LANE_RV#



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<Variant Name>



AAEON Technology INC.

Title

SoC Strap

Size

Document Number

A4

COM-TGUC6

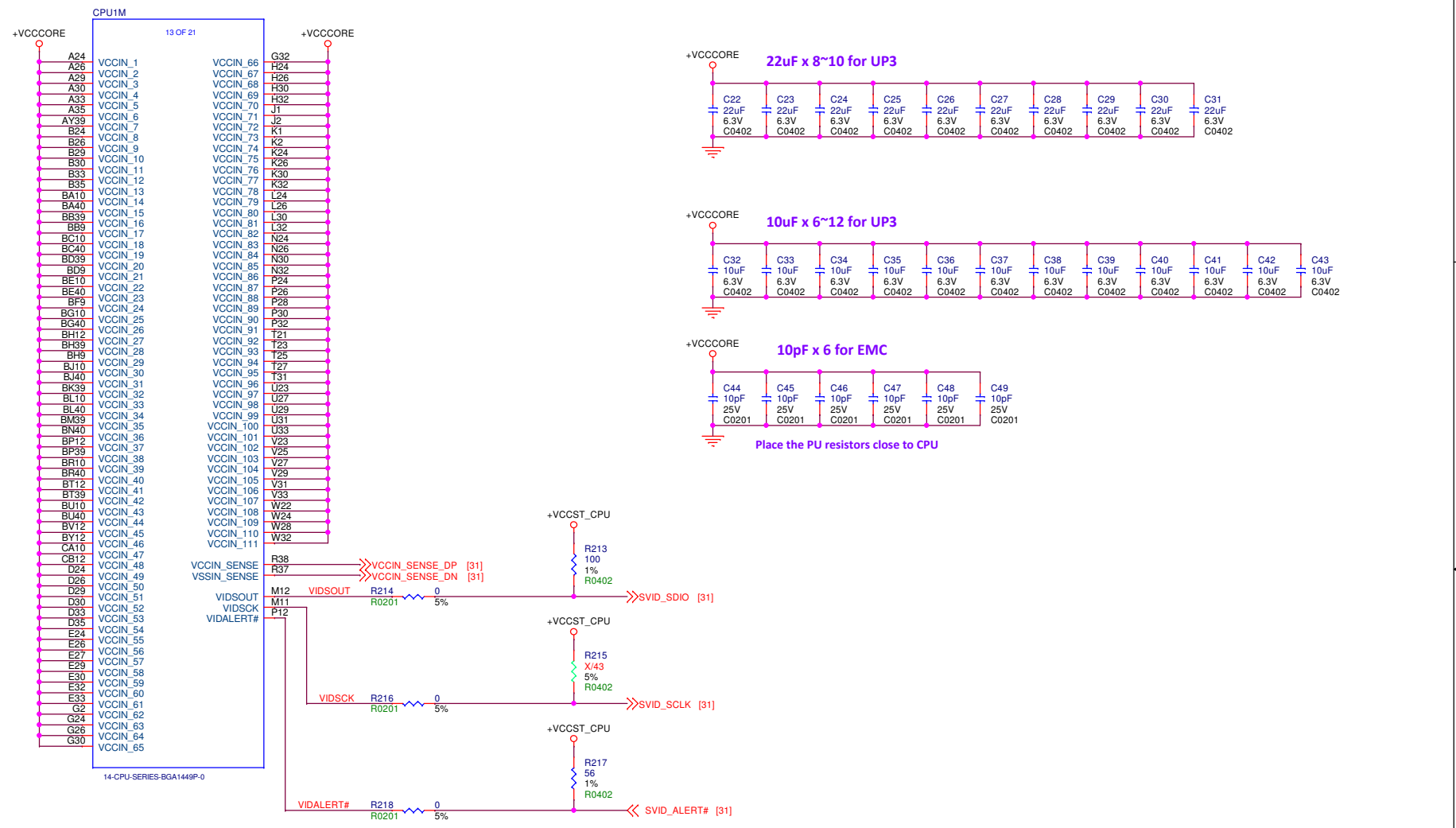
Rev

A0.2_0_0

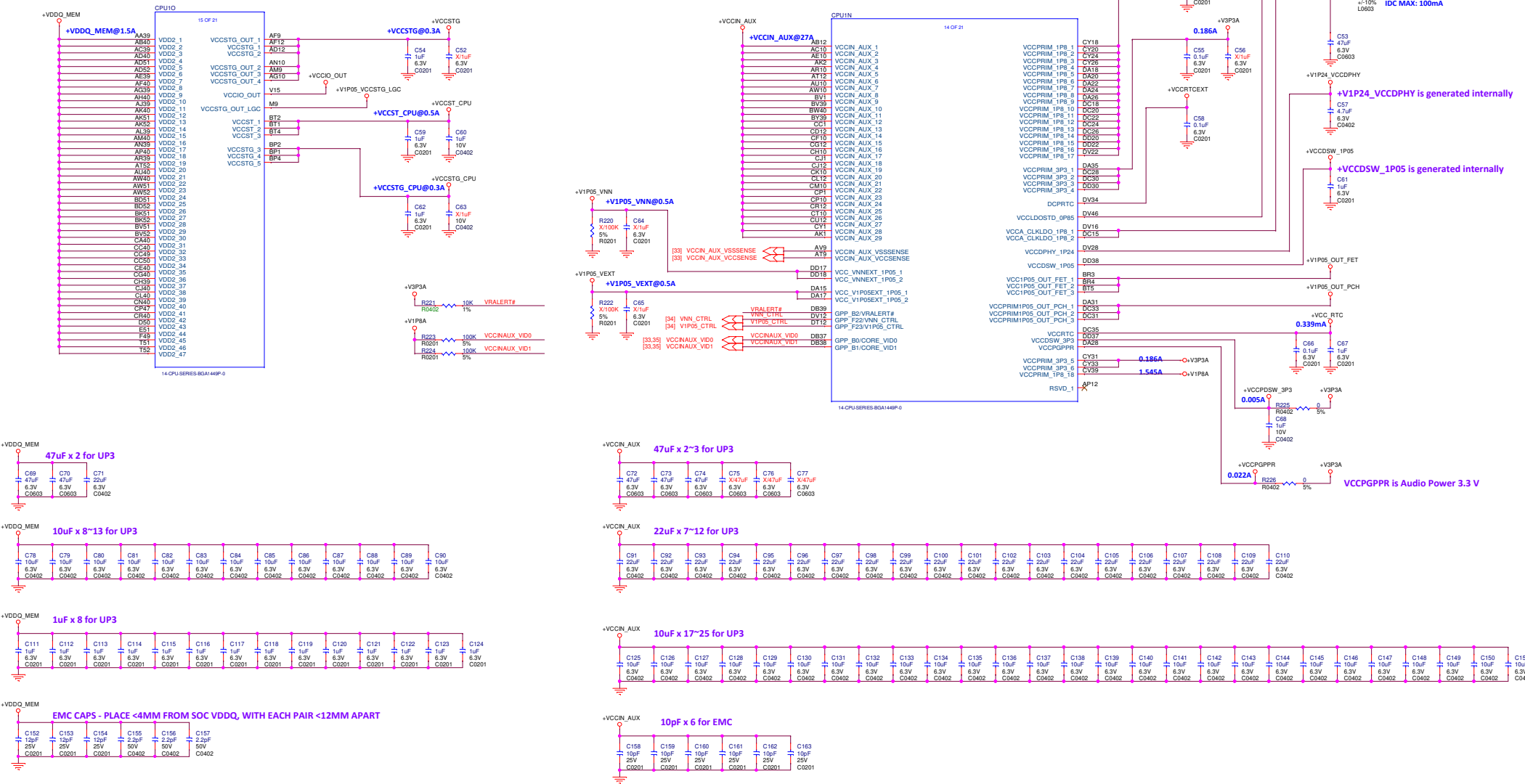
Monday, November 23, 2020

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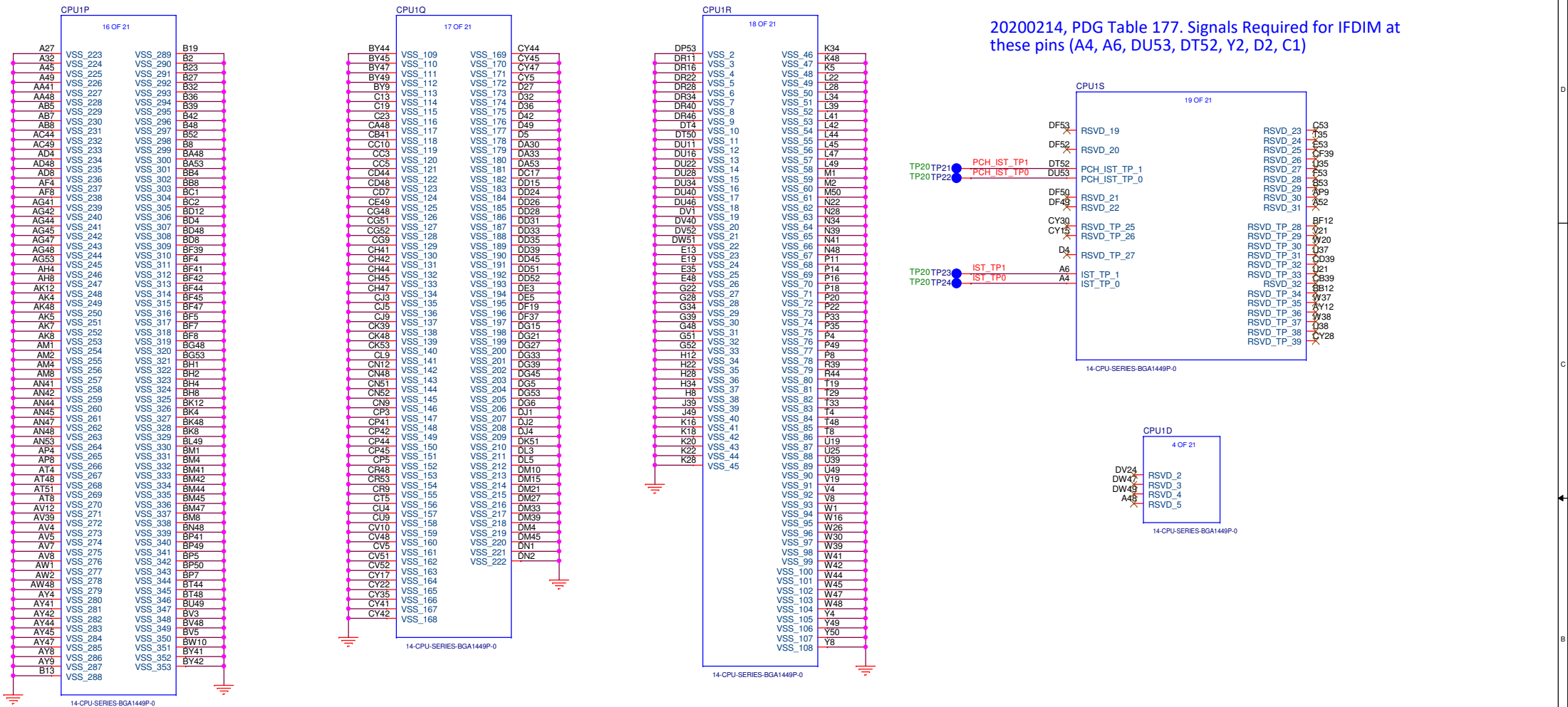
SoC Power

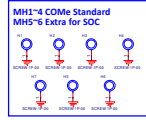
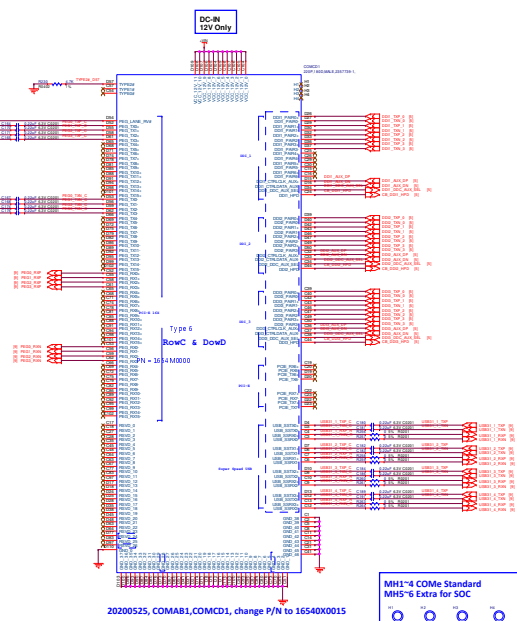
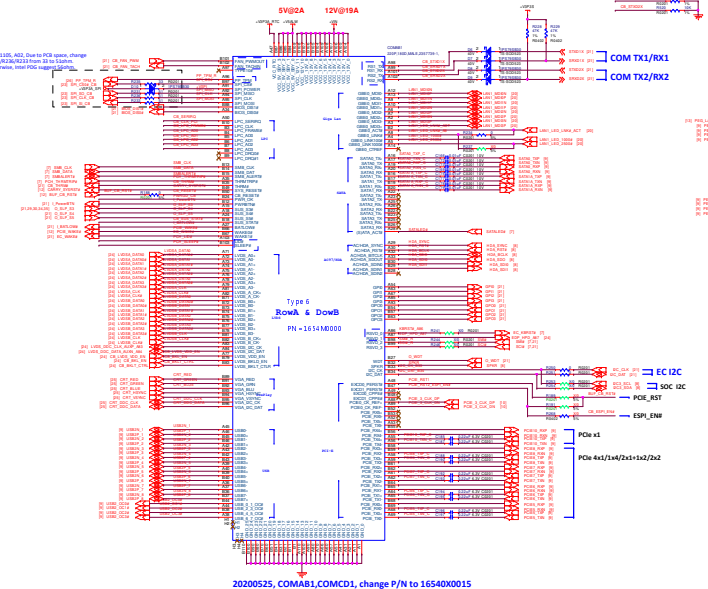
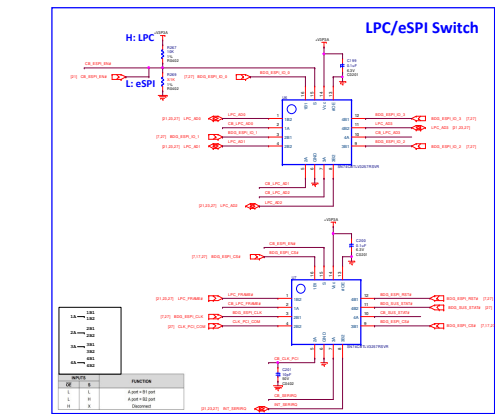
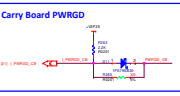
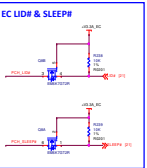


PCH Power

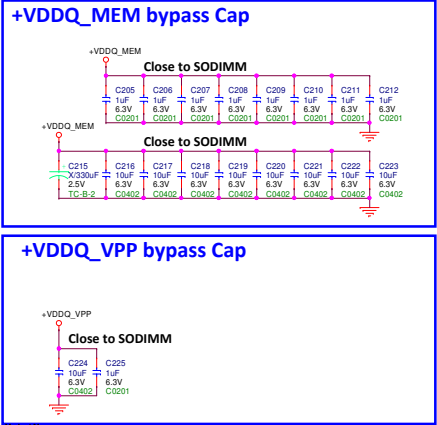
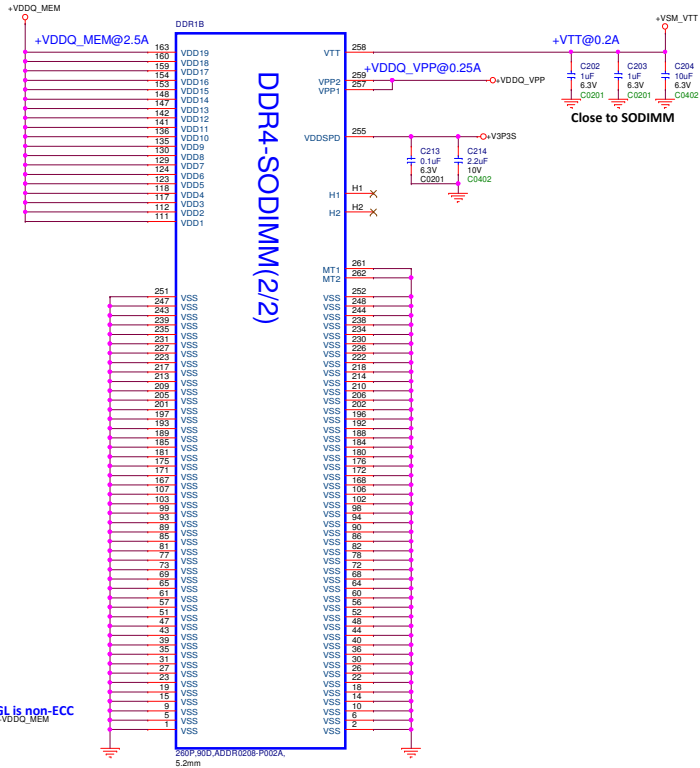


SoC GND

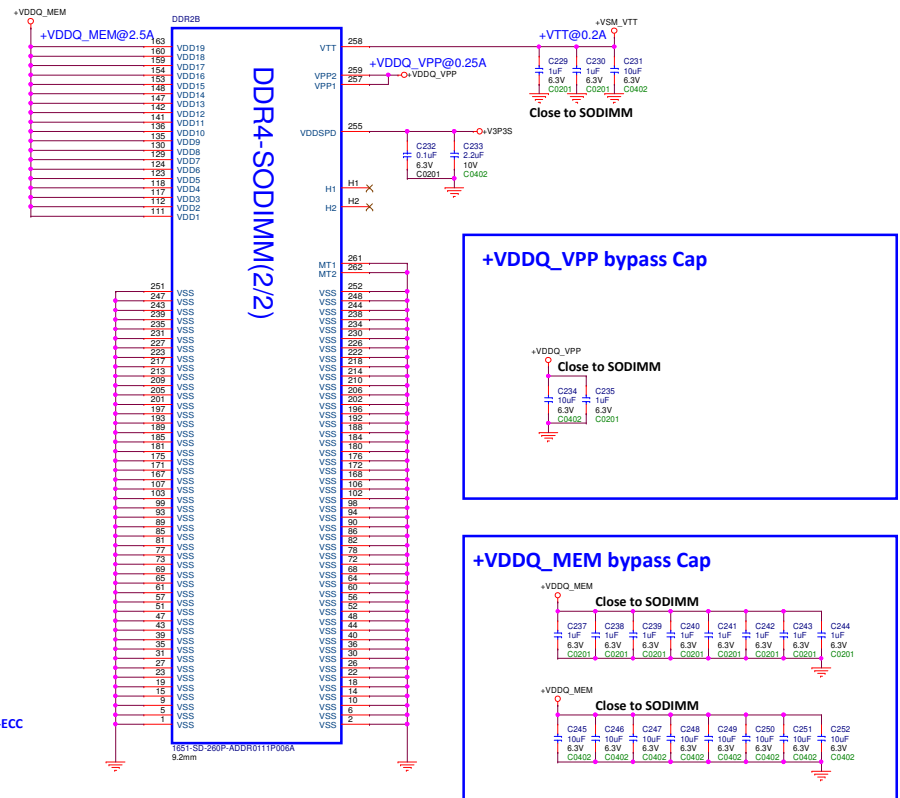
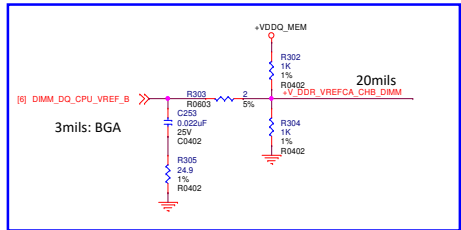




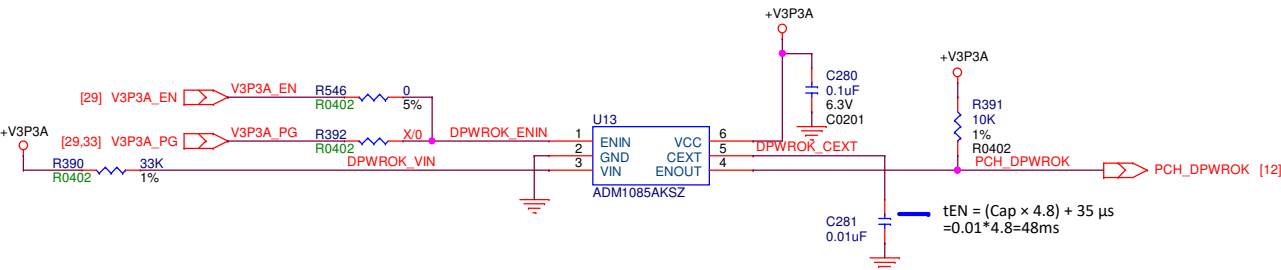
H= 5.2mm



H=9.2mm



DSW_PWROK Control



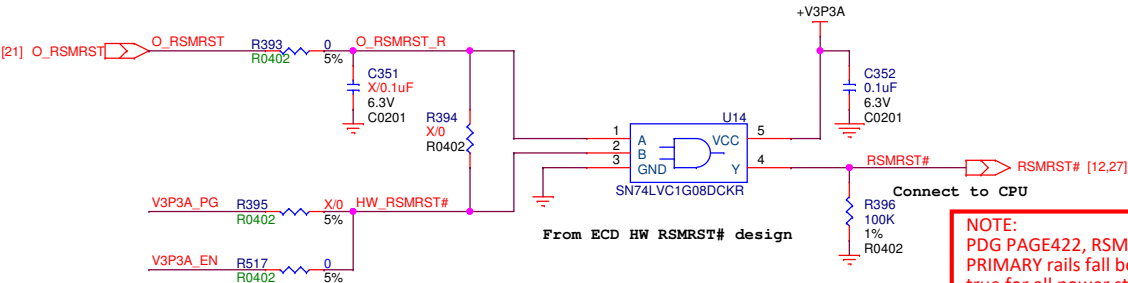
$3.3V \times 10 / (10+33) = 0.767$

ENIN VIH = 0.3*VCC+0.2 =1.19V
ENIN VIL = 0.3*VCC- 0.2 = 0.79V
ENOUT/ENOUT# Voltage Low (MAX =0.4V),When
Vin < Vth_falling (ENOUT) / Vin > Vth_rising
(ENOUT#)

Table 2.

Parameter	Min	Typ	Max	Unit	Test Conditions/Comments
SUPPLY					
V _{CC} Operating Voltage Range	2.25		3.6	V	
V _{IN} Operating Voltage Range	0		22	V	
Supply Current		10	15	μA	
V _{IN} Rising Threshold, V _{TH_RISING}	0.56	0.6	0.64	V	V _{CC} = 3.3 V
V _{IN} Falling Threshold, V _{TH_FALLING}	0.545	0.585	0.625	V	V _{CC} = 3.3 V
V _{IN} Hysteresis		15		mV	

RSMRST# Control

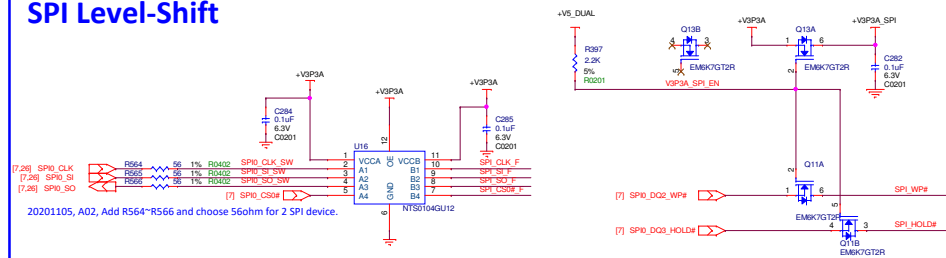


NOTE:
PDG PAGE422, RSMRST# must always be driven low before any of the
PRIMARY rails fall below the lower end of their tolerance band. This is
true for all power states transitions including emergency power loss.
RSMRST# is de-asserted by EC of O_RSMRSTon G3->S5, Asserted by
VR of V3P3A_EN at S5->G3 before VccPRIM dropping.

<Variant Name>

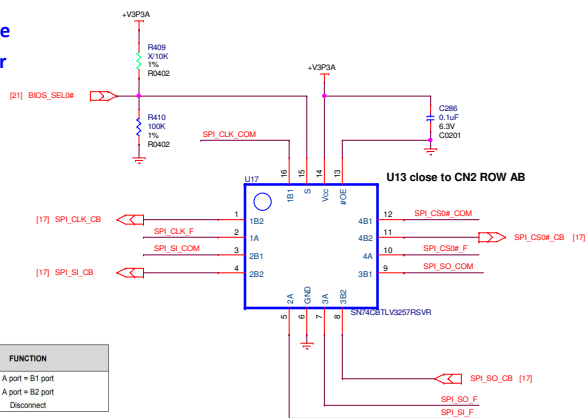
AAEON Technology INC.			
Title RSMEST# Control			
Size B	Document Number COM-TGUC6	Rev	A0.2_0_0
Date: Monday, November 23, 2020	Sheet 22	of	36

SPI Level-Shift



BIOS Switch MB/CB

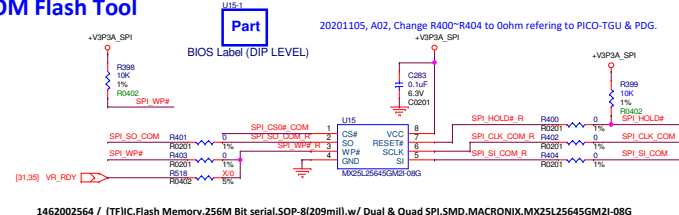
L: Module
H: Carrier



INPUTS		FUNCTION
OE	S	
L	L	A port = B1 port
L	H	A port = B2 port
H	X	Disconnect

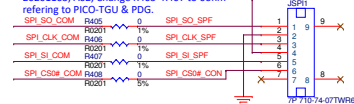
SPI ROM Flash Tool

20200526, Add BIOS Label



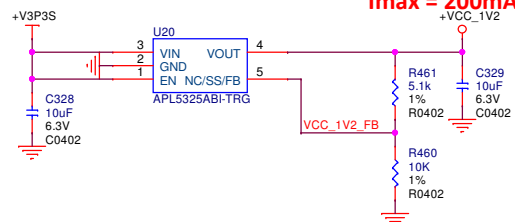
+V3P3A_SPI

20201105, A02, Change R405
referring to PICO-TGU & PDG.



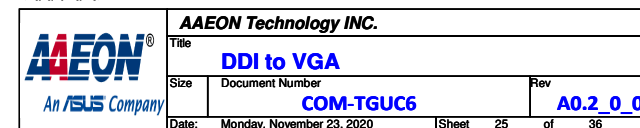
20201105, A02, Remove JLC1 circuit (80 port conn.) for the PCB spacing of EEPROM of Intel i225.

1. +1.05V power supply tolerance range -5%~+25%
2. +3.3V power supply tolerance range +/-10%



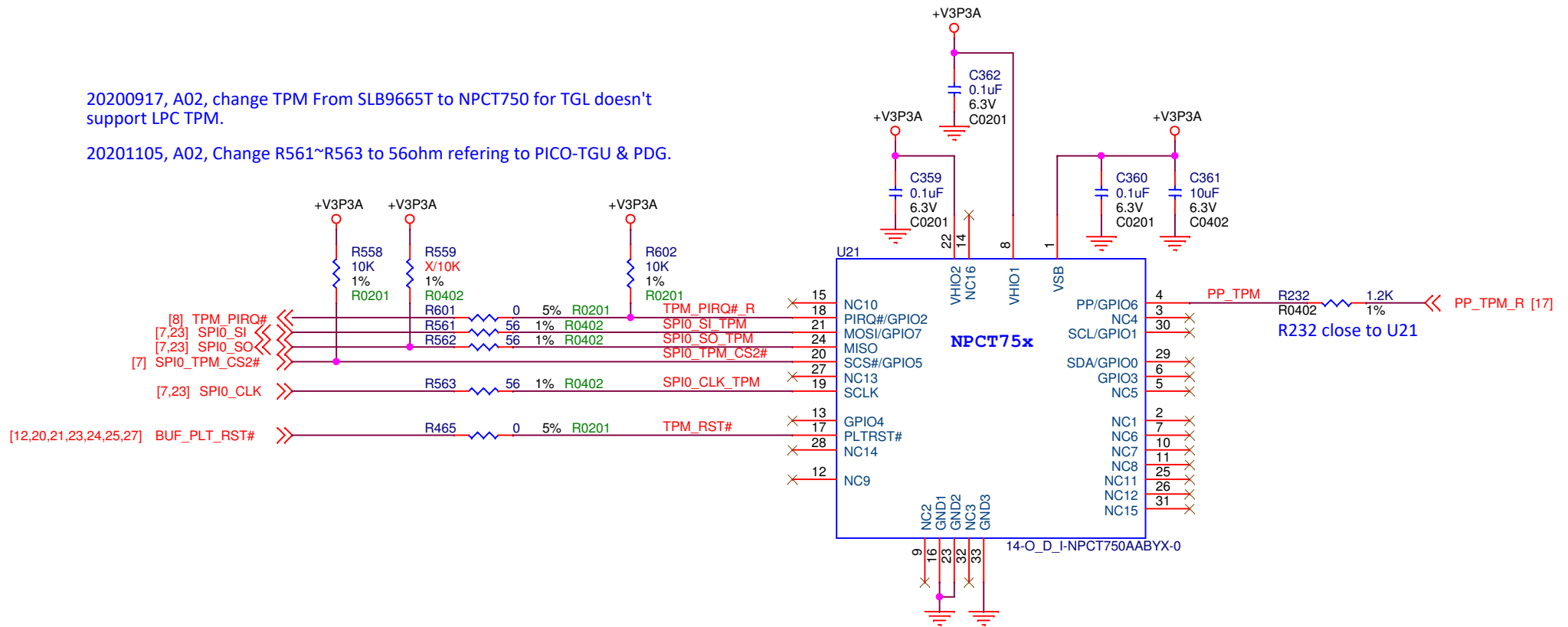
20201007, A02, Change value of C327/C326 from 20pF to 12pF and add R571 for FAE suggestion.

20201110, A02, After confirm with Jake, change R571 from 1.8k ohm(0402) to R54 1k (0201).




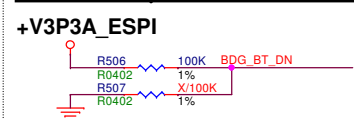
20200917, A02, change TPM From SLB9665T to NPCT750 for TGL doesn't support LPC TPM.

20201105, A02, Change R561~R563 to 56ohm referring to PICO-TGU & PDG.



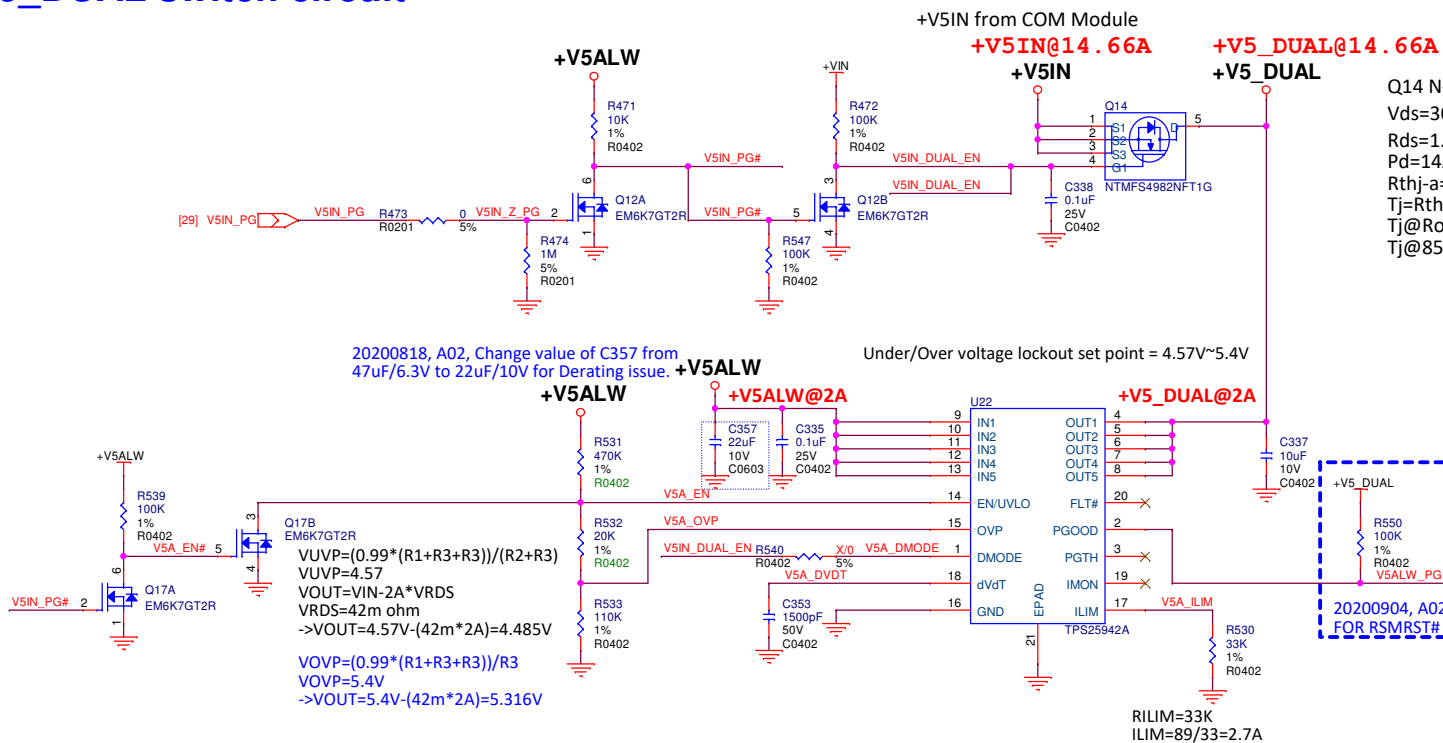
<Variant Name>

 An ASUS Company		AAEON Technology INC.	
		Title	TPM
Size	Document Number	Rev	A0.2_0_0
Date:	Monday, November 23, 2020	Sheet	26 of 36



<Variant Name>

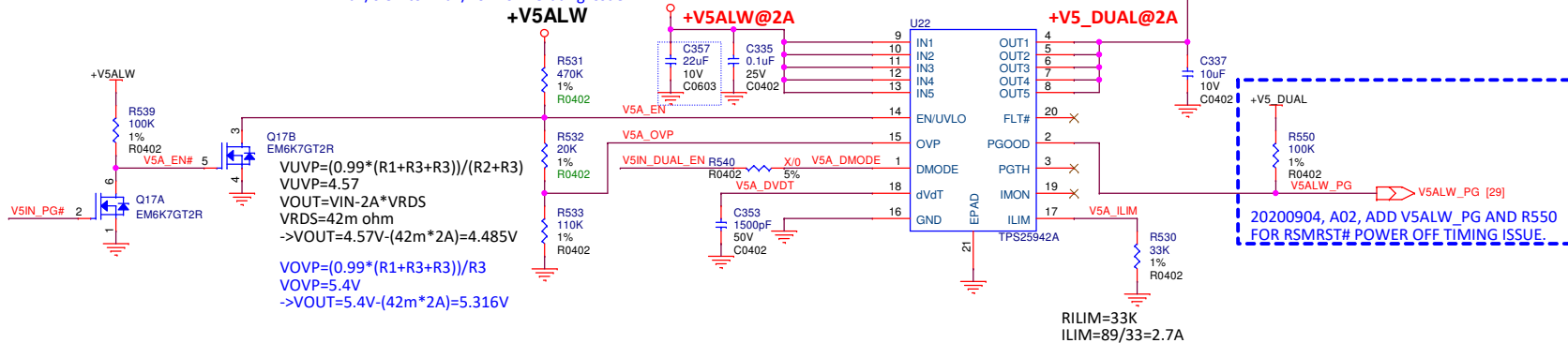
+V5_DUAL switch circuit



Q14 N-Ch / 1315049820
Vds=30V.Vgs=(+/-)20V.Ids=36A.Rds=1.9mohm.DFN5 5x6
Rds=1.9mR
Pd=14A*14A*1.9mR=0.37W
Rthj-a=46.6 degreeC
Tj=Rthj-a*Pd+Temp(25 or 85)
Tj@Room= 46.6*0.37+25=42 degreeC(<150 degree C)
Tj@85 degreeC=46.6*0.37+85=102 degreeC(<150 degree C)

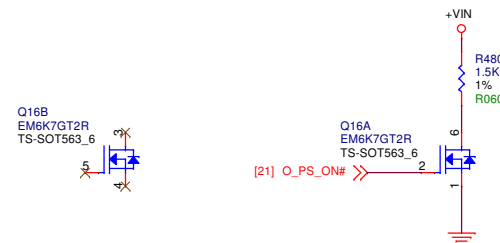
20200818, A02, Change value of C357 from 47uF/6.3V to 22uF/10V for Derating issue. +V5ALW

Under/Over voltage lockout set point = 4.57V~5.4V

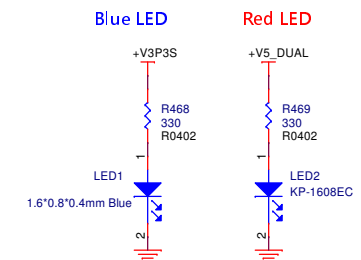


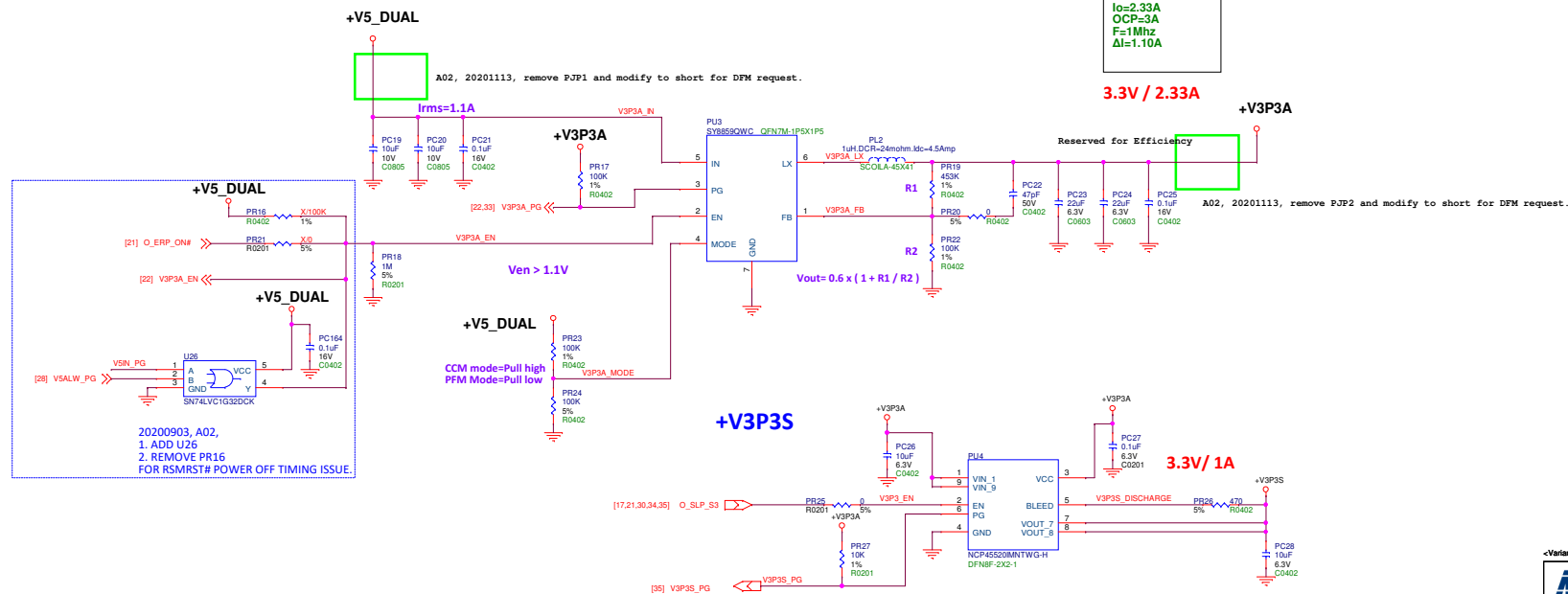
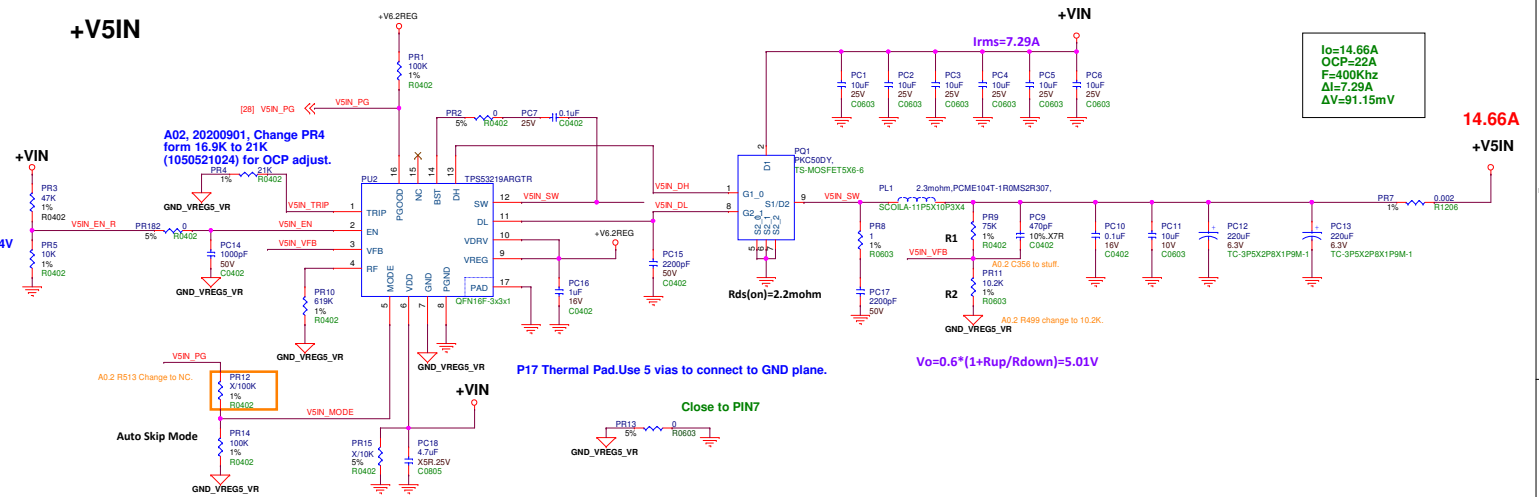
	+V5ALW	V5A_EN S5 -> S0
ATX	true	H -> L
AT with 5VSB	true	H -> L
AT without 5VSB	false	L -> L (U22 Always disable)

Discharge Circuit

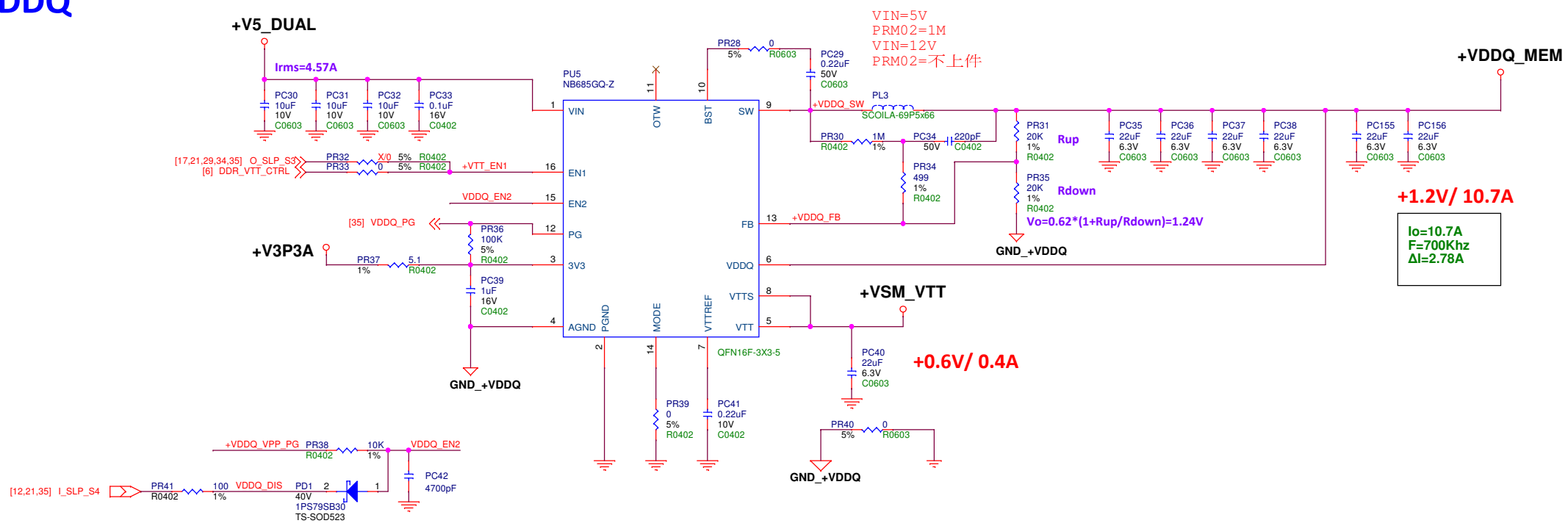


LED

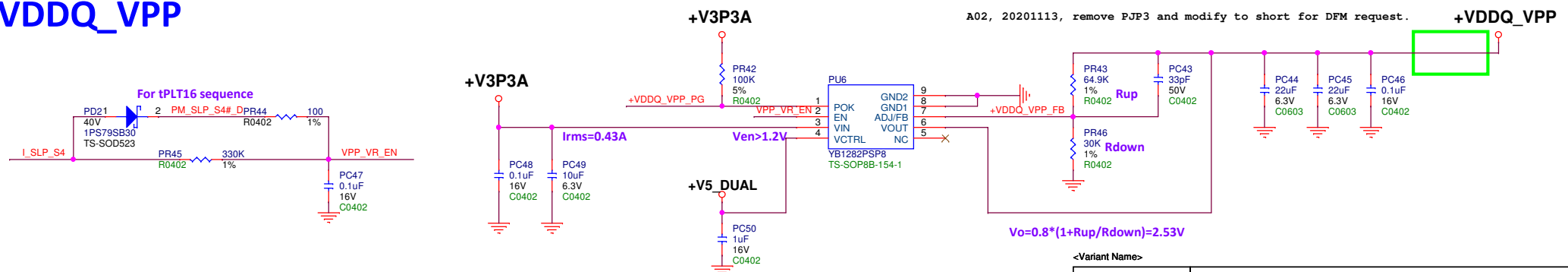




+VDDQ

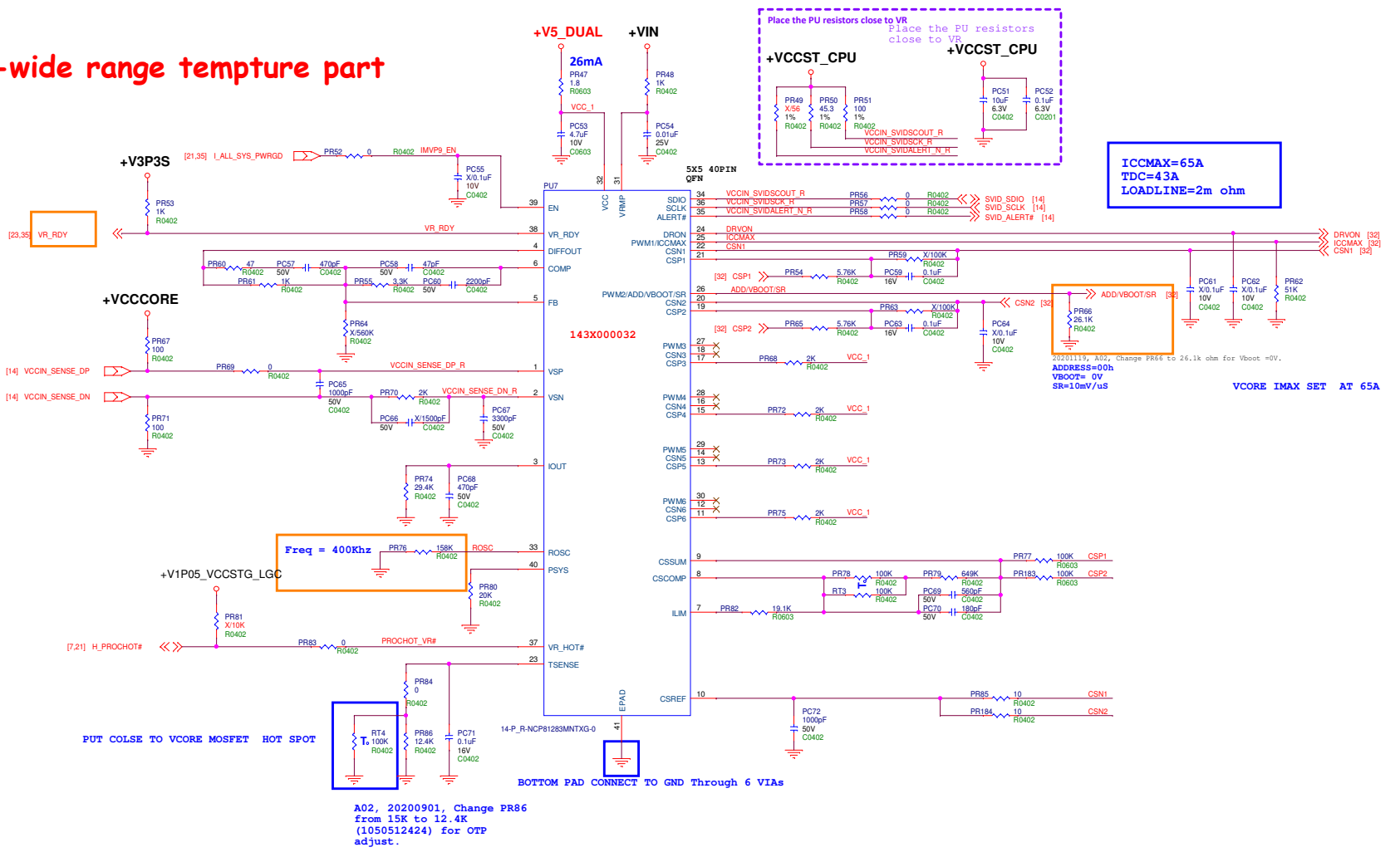


+VDDQ_VPP

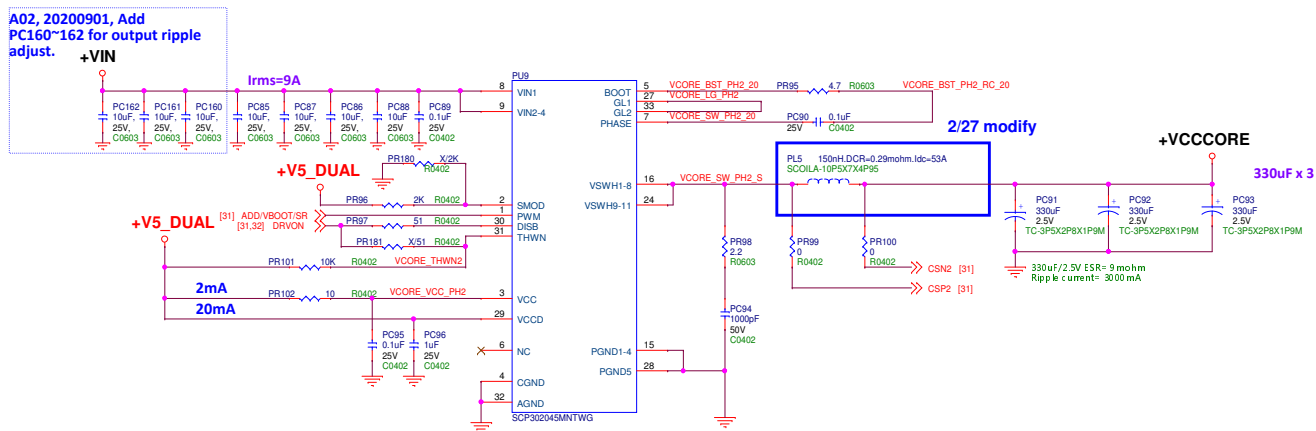
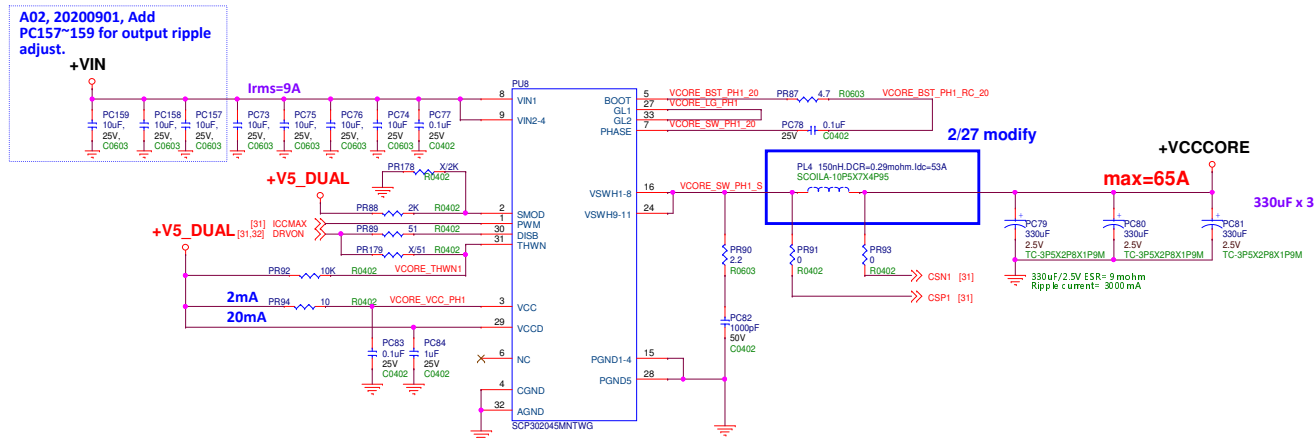


Tiger Lake IMVP9

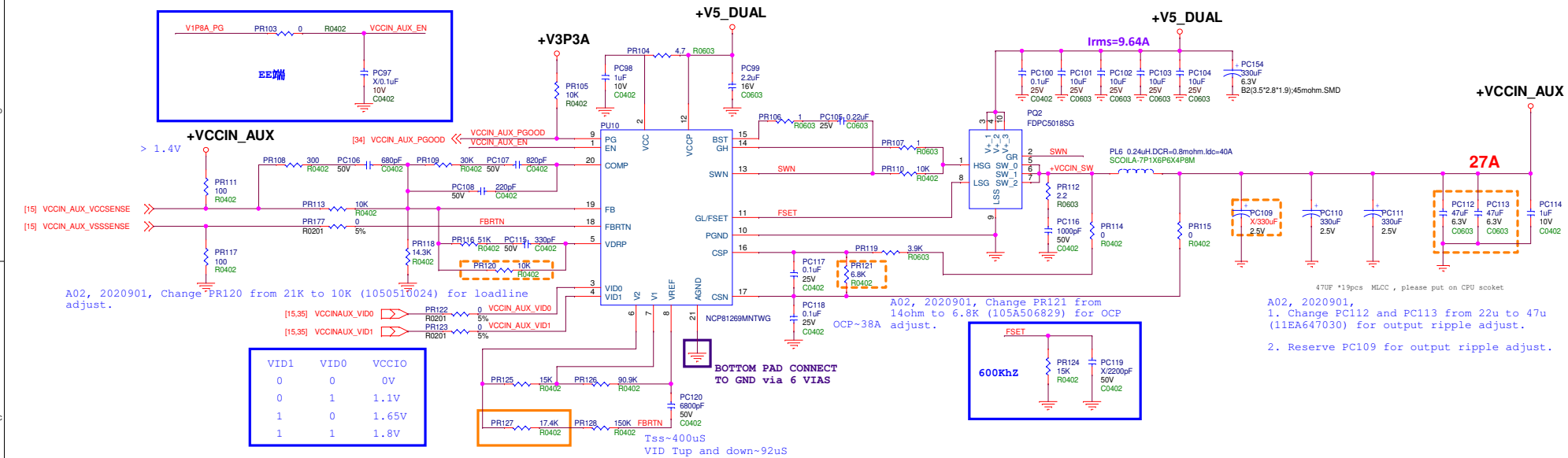
143X000032 is non-wide range tempture part



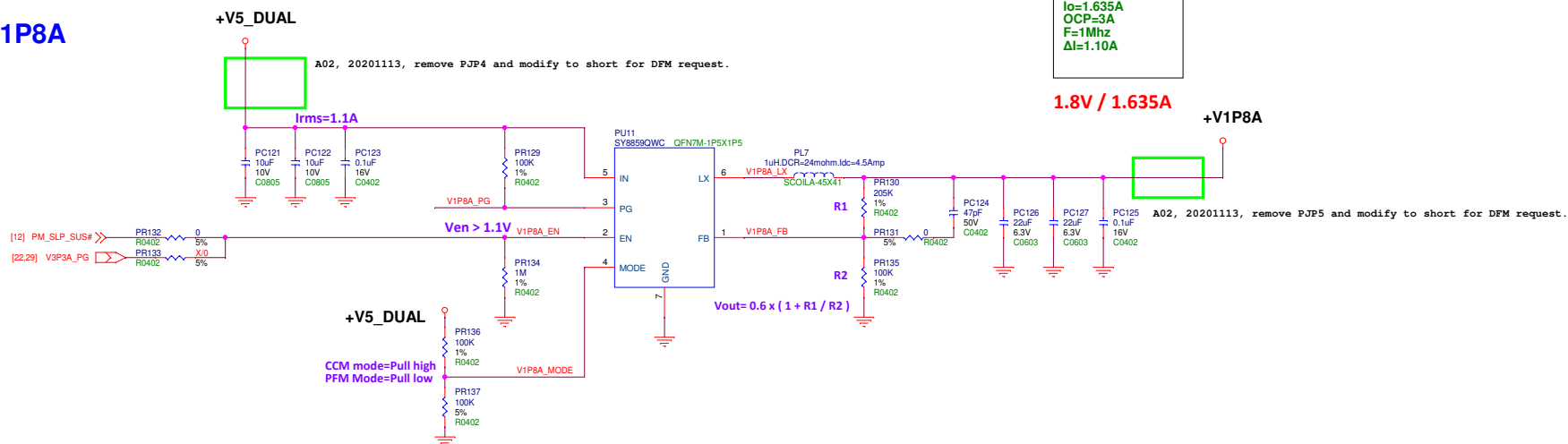
+VCCIN



+VCCIN_AUX



+V1P8A



D1 Project code: 1191711
D2 Model name: COM-TGUC6
D3 Model revision: A0.2_0_0
D4 3D-Level: 9697TGLU01
D5 PCB 料號: 1907TGLU01
D6 PCB 厚度: 2.0 mm
D7 PCB 層數: 14 Layer
D8 總板數目: 2 pcs

Revision History

Item	Page#	Title	Date	Request Owner	Issue Description	Solution Description	Rev.	Bug ID
1	5	DDI AUX SW	09/24	HW	Downsize SWth IC for Saving PCB space	Change P/N of U3 from 145S312500 to 1420USB300.	A02	
2	6	PWR sequence	09/21	HW	Mismatch PWR sequence	Due to cap. of IC, change value of R41 from 100k to 1k to meet power sequence.	A02	
3	7	1.No use function 2.Hang code SD in AT mode	09/22	HW	1.The eSPI ALERT# is including in eSPI IO pin and CPU don't have eSPI ALERT# pin. 2.AT ON/OFF test issue (hang 5d).	Remove BDG_ESPI_ALT_3P3# level-shift (R107, Q6, R106). The eSPI IO1 presents the ALERT# state while the eSPI bus is idle by datasheet. And resolve AT problem.	A02	
4	7	Change to SPI TPM	09/30	HW	Change TPM IC from LPC to SPI, cuz Tiger Lake don't support LPC TPM. Adjust SPI circuit for supporting two SPI device.	Add SP10_ TPM_CS#, Change serie R568 / R569 / R570 to 5.1ohm for SP10_CLK / SP10_S0 / SP10_SI.	A02	
5	7	Change Level-shifter	09/21	HW	CUZ the VIH (1.05V) of NMOS is too margin, change IC to avoid it.	Change U6 level shifter to 145901G070.	A02	
6	7	LAN I2C	11/06	HW	Change R value for Intel I225.	Change R46 / R47 from 1k to 499 to meet I225 checklist.	A02	
7	8	Debug	07/17	HW	Reserve UART test point for Debugging BIOS.	Add TP30~TP33 for BIOS request.	A02	
8	8	Save PCB space	11/05	HW	Remove parts to save PCB space	The nets of CPU1_D129 & CPU1_DJ31 (I2C function for 80 pin) for the PCB spacing of EEPROM of Intel I225.	A02	
9	9	USB OC# pin	09/24	HW	Change design for USB OC# pin for multi-OC# pin.	Add D17~D20 & change OC NETdesign for USB OC PIN OUT issue	A02	
10	9	Change placement	11/06	HW	I225 checklist mentioned TX cap need to close to CPU.	Change C11/C12 placement for I225.	A02	
11	10	Change XTAL	0911	HW	After vendor measurement result, change XTAL & cap.	1. Change P/N of Y1 from 1231327631 to 1231327632 by test result. 2. Change P/N of Y2 from 1231039450 to 1231039451 by test result. 3. Change value of C18/C19 from 15pF to 15pF by test result.	A02	
12	12	LAN Wake pin	11/06	HW	Pull up 10kohm based on I225 CRB.	Mount R162 for I225.	A02	
13	17	SPI serie R	11/05	HW	Adjust SPI circuit for supporting two SPI device.	Due to PCB space, change R231/R236/R233 from 33 to 51ohm. Otherwise, Intel PDG suggest 56ohm.	A02	
14	31	Vboot	11/19	HW	Choose correct Vboot value	Change PR66 to 26.1k ohm for Vboot -0V.	A02	
15	20	LAN I225	11/06	HW	Due to PM modifying spec. change LAN form I219 to I225.	Add U29 w/ Peripheral Circuitry. ADD Q20 CIRCUIT FOR LAN LED LEAKAGE ISSUE	A02	
16	21	Multi-change for saving PCB space	11/11	HW	Change parts to save PCB space for I225.	1. Change AT/ATX SW to R603 & R604. 2. Remove Q10 & Q9 & R381 & R382 & JECSP11. 3. Change U12 to small package. PN:145801G070 4. Change R347 & R344 to Q201 package.	A02	
17	23	1.SPI serie R 2.Spacing PCB space	11/05	HW	1.Adjust SPI circuit for supporting two SPI device. 2. Modify parts to save PCB space.	1. Add R564~R566 and choose 56ohm for 2 SPI device. Change R400~R404 and R405~R407 to 0ohm referring TCGO-UG & PDG. 2. Remove J1PC1 circuit (80 port conn.) for the PCB spacing of EEPROM of Intel I225.	A02	
18	24	LVDS CTRL Signals	0922	HW	Modify the circuit of LVDS back light control and EDP_VDD_EN for eDP and LVDS.	1. add R548 and connect the net of EDP_BKLT_CTRL to U18.I2 for LVDS back light control. 2. Change U25 from 14GLVDS271 to 1420USB300 for IC downsizing. 3. Add EDP_VDD_EN, EDP_BKLT_CTRL and EDP_VDD_EN by BIOS request for eDP2 black light control. 4. Add Q19 to disable LVDS and pull HPD of DDIA to Low, when EDP_HPDI PULL HIGH. 5. Add OR GATE U27 to enable LVDS/EDP_VDD_EN/	A02	
19	25	XTAL modification	10/07	HW	After vendor measurement result, change cap and add R.	1. Change value of C327/C326 from 20pF to 12pF and add R571 for FAE suggestion. 2. After confirm with Jake, change R571 from 1.8k ohm(0402) to R54 1k (0201).	A02	
20	26	SPI TPM	11/05	HW	Change TPM IC from LPC to SPI, cuz Tiger Lake don't support LPC TPM.	change TPM U21 From SLB9665T to NPCT750 for TGL doesn't support LPC TPM.	A02	
21	27	ECE1200	11/05	HW	Debug eSPI to LPC IC and add solution.	1. Connecting BDG_SUSWARN# and BDG_SUSACK# with R497 for boot up issue by FAE request. 2. ADD R567 to PU ESPI ALT. The eSPI IO1 presents the ALERT# state while the eSPI bus is idle. 3. Remove R467 which connect to J1PC1 for the PCB spacing of EEPROM of Intel I225.	A02	
22	28	PWR	09/04	HW	Denting issue and PWR sequence solution.	1. Change value of C367 from 47uF/6.3V to 22uF/10V for Denting issue. 2. ADD VSALW_PG AND R550 FOR RSMRST# POWER OFF TIMING ISSUE.	A02	
23	29	PWR	09/01	HW	Adjust OCP value.	Change PR4 form 16.9K to 21K (1050521024) for adjusting OCP.	A02	
24	28	PWR	09/04	HW	PWR sequence solution for RSMRST# POWER OFF.	1. ADD U26 2. REMOVE PR16 FOR RSMRST# POWER OFF TIMING ISSUE.	A02	
25	29 & 30 & 33	Shor pad	09/04	HW	Remove short pad for PE suggestion.	Remove P1P1 / P1P2 / P1P3 / P1P4 / P1P5 and modify to short for DFM request.	A02	
26	31	PWR	09/01	HW	Adjust OTP value.	Change PR86 from 15K to 12.4K (1050512424) for adjusting OTP.	A02	
27	32	PWR	09/01	HW	Add caps after fine tuning output ripple.	1. Add PC157~159 for output ripple. 2. Add PC160~162 for output ripple.	A02	
28	33	PWR	09/01	HW	Change R after fine tuning loadline and OCP value.	1. Change PR120 from 21K to 10K (1050510024) for loadline. 2. Change PR121 from 14ohm to 6.8K (105A506829) for OCP. 3. Change PC112 and PC113 from 22u to 47uF (11E647030) for output ripple. 4. Reserve PC109 for output ripple.	A02	
29	34	PWR	09/01	HW	Add caps after fine tuning output ripple.	Add PC163 (11E9622080) for ripple.	A02	
30	35	Sighting report #632245	09/01	HW	Due to improper initialization of logic on the VCCST power domain in the Tiger Lake-UP3, the system may fail to exit S3.	Add PR6 & PR155 for Workaround.	A02	